

ABSTRACT

The present invention relates to a substrate processing apparatus for processing a substrate, such as a wafer, and more particularly to a substrate processing method and a substrate processing apparatus for polishing a bevel portion of the substrate and
5 performing CMP processing of a flat portion of the substrate. The substrate processing method includes: polishing a bevel portion (B) of each of the plurality of substrates (W) by a polishing tool such that slope surfaces (S) of bevel portions (B) of the plurality of substrates (W) have the same slope angles (α); and performing CMP processing of a flat portion (P) of each of the plurality of substrates (W) whose bevel portions (B) have been
10 polished.

FIG. 5